

L Number	Hits	Search Text	DB	Time stamp
-	114936		USPAT;	2002/04/17 16:27
		"3-D" or "3 D" or "three-dimensional" or	US-PGPUB	
		"3-dimensional"		
-	923	("three dimensional" or "3 dimensional" or	USPAT;	2002/04/17 16:33
	1	"3-D" or "3 D" or "three-dimensional" or	US-PGPUB	
		"3-dimensional") and ((bond or bonding)		
		SAME "thin film")		ŀ
_	274	(("three dimensional" or "3 dimensional"	USPAT;	2002/04/17 16:33
		or "3-D" or "3 D" or "three-dimensional"	US-PGPUB	
		or "3-dimensional") and ((bond or bonding)		
		SAME "thin film")) and (UV or irradiating		
		or irradiate)		
-	157	((("three dimensional" or "3 dimensional"	USPAT;	2002/04/17 16:31
		or "3-D" or "3 D" or "three-dimensional"	US-PGPUB	
		or "3-dimensional") and ((bond or bonding)		
		SAME "thin film")) and (UV or irradiating		
		or irradiate)) and semiconductor		
-	3417	transfer with substrate with device	USPAT;	2002/04/17 16:32
			US-PGPUB	
-	4068	(transfer or transferring) with substrate	USPAT;	2002/04/17 16:32
		with device	US-PGPUB	
-	331	((transfer or transferring) with substrate	USPAT;	2002/04/17 16:32
		with device) and ("three dimensional" or	US-PGPUB	
		"3 dimensional" or "3-D" or "3 D" or		
		"three-dimensional" or "3-dimensional")		
	121	(((transfer or transferring) with	USPAT;	2002/04/17 17:00
		substrate with device) and ("three	US-PGPUB	
		dimensional" or "3 dimensional" or "3-D"		
		or "3 D" or "three-dimensional" or		
		"3-dimensional")) and "thin film"		1
_	55	((((transfer or transferring) with	USPAT;	2002/04/17 16:33
	35	substrate with device) and ("three	US-PGPUB	2002/04/1/ 10:55
		dimensional" or "3 dimensional" or "3-D"	05 10105	1
		or "3 D" or "three-dimensional" or		1
		"3-dimensional")) and "thin film") and (UV		
		or irradiating or irradiate)		
_	66		USPAT;	2002/04/17 17:08
· · · · · · · · · · · · · · · · · · ·	00	substrate with device) and ("three	US-PGPUB	2002/04/17 17.00
		dimensional" or "3 dimensional" or "3-D"	03.10100	1
		or "3 D" or "three-dimensional" or	1	
		"3-dimensional")) and "thin film") NOT	1	1
		(((((transfer or transferring) with		
		substrate with device) and ("three		!
		dimensional" or "3 dimensional" or "3-D"	1	
		or "3 D" or "three-dimensional" or "3-dimensional")) and "thin film") and (UV	1	
		or irradiating or irradiate))		1
	20		HODAM.	2002/04/17 10:02
_	28	"thin film device" SAME transfer SAME	USPAT;	2002/04/17 18:02
	1.00	substrate	US-PGPUB	2002/04/17 10 03
_	1605	"thin film" SAME transfer SAME substrate	USPAT;	2002/04/17 18:03
		(11)	US-PGPUB	1000010115
-	835	("thin film" SAME transfer SAME substrate)	USPAT;	2002/04/17 18:03
		and (bonding or bonded or bond)	US-PGPUB	
-	502	(("thin film" SAME transfer SAME	USPAT;	2002/04/17 18:06
V-4		substrate) and (bonding or bonded or	US-PGPUB	İ
		bond)) and semiconductor		1
-	3	("5821138" "6127199" "6143582").PN.	USPAT	2002/04/17 18:14